RoHS

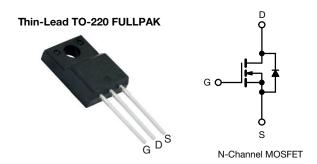
COMPLIANT

FREE



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EF Series Power MOSFET with Fast Body Diode



PRODUCT SUMMA	RY	
V _{DS} (V) at T _J max.	650)
$R_{DS(on)}$ max. (Ω) at 25 °C $V_{GS} = 10 \text{ V}$		0.176
Q _g max. (nC)	84	
Q _{gs} (nC)	14	
Q _{gd} (nC)	24	
Configuration	Sing	le

FEATURES

- Fast body diode MOSFET using E series technology
- Reduced t_{rr}, Q_{rr}, and I_{RRM}
- Low figure-of-merit (FOM): Ron x Qg
- Low input capacitance (Ciss)
- Increased robustness due to low Q_{rr}
- Ultra low gate charge (Q_a)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Telecommunications
 - Server and telecom power supplies
- Lighting
 - High intensity discharge (HID)
 - Light emitting diodes (LEDs)
- Consumer and computing
 - ATX power supplies
- Industrial
 - Welding
 - Battery chargers
- Renewable energy
- Solar (PV inverters)
- Switch mode power suppliers (SMPS)
- Applications using the following topologies
 - LLC
 - Phase shifted bridge (ZVS)
 - 3-level inverter
 - AC/DC bridge

ORDERING INFORMATION	
Package	Thin-Lead TO-220 FULLPAK
Lead (Pb)-free	SiHA21N60EF-E3
Lead (Pb)-free and halogen-free	SiHA21N60EF-GE3

ABSOLUTE MAXIMUM RATINGS (TC	= 25 °C, unless otherwis	se noted)		
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-source voltage		V_{DS}	600	V
Gate-source voltage	V_{GS}	± 30	7 °	
Continuous drain current (T _J = 150 °C)	V_{GS} at 10 V $T_{C} = 25 ^{\circ}C$ $T_{C} = 100 ^{\circ}C$		9	
	$T_C = 100 ^{\circ}$ C	ID	5	Α
Pulsed drain current ^a	I _{DM}	53		
Linear derating factor		0.28	W/°C	
Single pulse avalanche energy b		E _{AS}	367	mJ
Maximum power dissipation		P_{D}	35	W
Operating junction and storage temperature range	T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope	T _J = 125 °C	4).//d+	70	V/ns
Reverse diode dV/dt ^d	dV/dt	50	V/IIS	
Soldering recommendations (peak temperature) c	for 10 s		300	°C
Mounting torque	M3 screw		0.6	Nm

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. $V_{DD} = 50 \text{ V}$, starting $T_J = 25 \,^{\circ}\text{C}$, $L = 28.2 \,^{\circ}\text{mH}$, $R_g = 25 \,^{\circ}\Omega$, $I_{AS} = 5.1 \,^{\circ}\text{A}$
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, dI/dt = 900 A/ μ s, starting $T_J = 25$ °C

Document Number: 91597



Vishay Siliconix

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum junction-to-ambient	R _{thJA}	-	65	°C/W		
Maximum junction-to-case (drain)	R_{thJC}	-	3.6	[C/W		

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static		^			•	·	
Drain-source breakdown voltage	V _{DS}	V _{GS} :	= 0 V, I _D = 250 μA	600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Referenc	e to 25 °C, I _D = 1 mA	-	0.59	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2.0	-	4.0	V
Gate-source leakage	1	V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 30 \text{ V}$	-	-	± 1	μΑ
Zero gate voltage drain current			$V_{DS} = 480 \text{ V}, V_{GS} = 0 \text{ V}$		-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 \	$V_{\rm S} = 0 \ V_{\rm T} = 125 \ ^{\circ}{\rm C}$	-	-	500	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 11 A	-	0.153	0.176	Ω
Forward transconductance	9 _{fs}	V_{DS}	= 30 V, I _D = 11 A	-	7	-	S
Dynamic							
Input capacitance	C _{iss}		V _{GS} = 0 V,		2030	-	
Output capacitance	C _{oss}		$V_{DS} = 100 V,$	-	105	-	
Reverse transfer capacitance	C_{rss}		f = 1 MHz	-	5	-	
Effective output capacitance, energy related ^a	$C_{\text{o(er)}}$	V _{GS} = 0 V, V _{DS} = 0 V to 480 V		-	86	-	pF
Effective output capacitance, time related ^b	$C_{o(tr)}$			-	299	-	
Total gate charge	Qg			-	56	84	
Gate-source charge	Q _{gs}	$V_{GS} = 10 \text{ V}$ $I_D = 11 \text{ A}, V_{DS} = 480 \text{ V}$		-	14	-	nC
Gate-drain charge	Q _{gd}			-	24	-	
Turn-on delay time	t _{d(on)}			-	21	42	
Rise time	t _r	V _{DD} = 480 V, I _D = 11 A		-	31	62	ns
Turn-off delay time	t _{d(off)}	$R_g = 1$	$R_g = 9.1 \Omega, V_{GS} = 10 V$		59	89	
Fall time	t _f	1		-	27	54	
Gate input resistance	Rg	f = 1 MHz, open drain		0.2	0.56	1.2	Ω
Drain-Source Body Diode Characteristic	es						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	21	
Pulsed diode forward current	I _{SM}			-	-	53	A
Diode forward voltage	V _{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 11 \text{A}, V_{GS} = 0 \text{V}$		-	0.9	1.2	V
Reverse recovery time	t _{rr}				135	270	ns
Reverse recovery charge	Q _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 11 \text{ A},$ $dI/dt = 100 \text{ A/}\mu\text{s}, V_R = 400 \text{ V}$		_	0.76	1.52	μC
Reverse recovery current	I _{RRM}			-	11	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

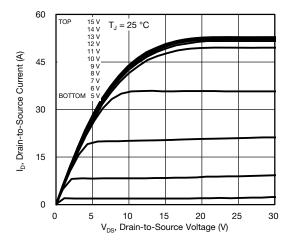


Fig. 1 - Typical Output Characteristics, T_J = 25 °C

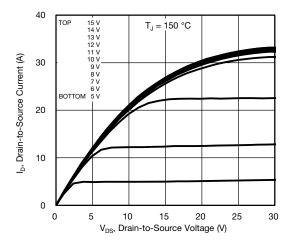


Fig. 2 - Typical Output Characteristics, T_J = 150 °C

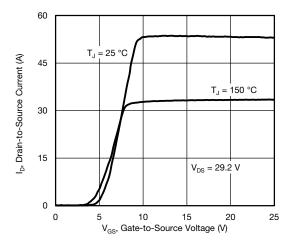


Fig. 3 - Typical Transfer Characteristics

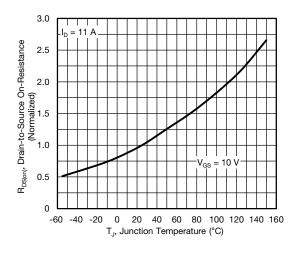


Fig. 4 - Normalized On-Resistance vs. Temperature

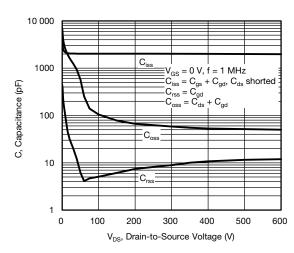


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

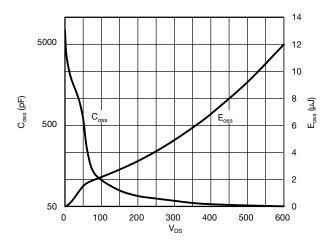


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



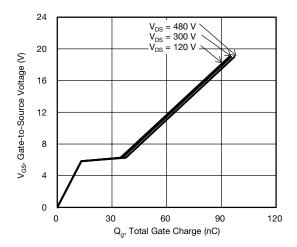


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

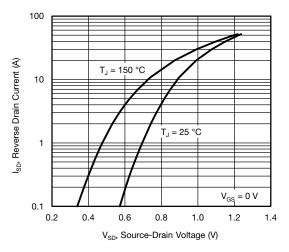


Fig. 8 - Typical Source-Drain Diode Forward Voltage

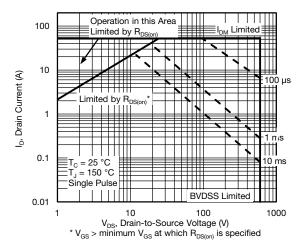


Fig. 9 - Maximum Safe Operating Area

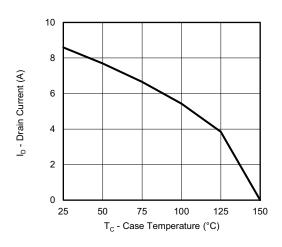


Fig. 10 - Maximum Drain Current vs. Case Temperature

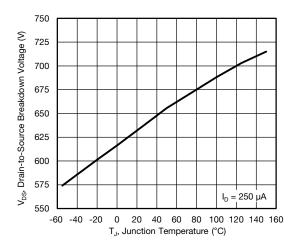


Fig. 11 - Typical Drain-to-Source Voltage vs. Temperature

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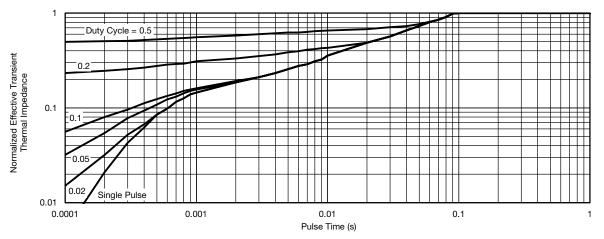


Fig. 12 - Normalized Thermal Transient Impedance, Junction-to-Case

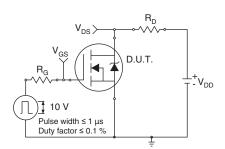


Fig. 13 - Switching Time Test Circuit

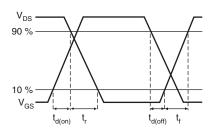


Fig. 14 - Switching Time Waveforms

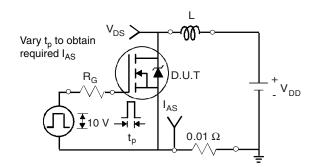


Fig. 15 - Unclamped Inductive Test Circuit

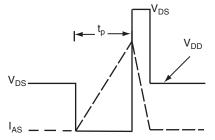


Fig. 16 - Unclamped Inductive Waveforms

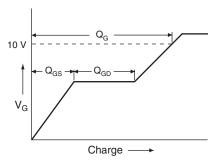


Fig. 17 - Basic Gate Charge Waveform

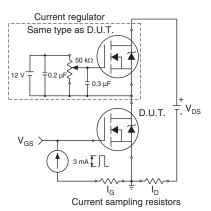
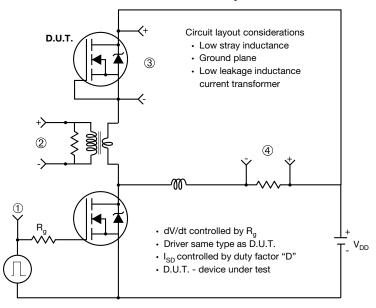


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



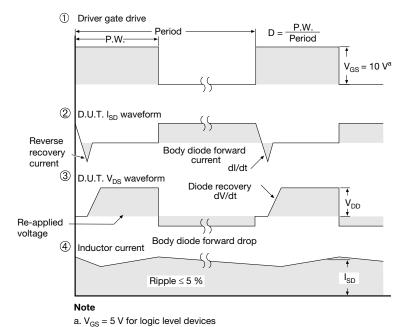


Fig. 19 - For N-Channel

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TO-220 FULLPAK Thin Lead





SYMBOL		DIMEN	ISIONS	
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
Α	4.30	4.70	0.169	0.185
A1	2.50	2.90	0.098	0.114
A2	2.40	2.80	0.094	0.110
b	0.60	0.80	0.024	0.031
b2	0.60	0.90	0.024	0.035
С	=	0.60	-	0.024
D	8.30	8.70	0.327	0.342
d1	14.70	15.30	0.579	0.602
d2	2.90	3.10	0.114	0.122
d3	3.30	3.70	0.130	0.146
Е	9.70	10.30	0.382	0.406
е	2.50	2.70	0.098	0.106
L	13.40	13.80	0.528	0.543
L1	1.00	2.80	0.039	0.110
ØP	3.00	3.40	0.118	0.134

ECN: E20-0684-Rev. D, 28-Dec-2020

DWG: 6021



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